





TITANIUM NITRIDE Sputtering Target

TiN sputtering targets are used to make coatings, which are for edge retention and corrosion resistance on machine tooling, such as drill bits and milling cutters, often improving their lifetime by a factor of three or more. TiN are also used in microelectronics, where they serve as a conductive connection between the active device and the metal contacts used to operate the circuit, while acting as a diffusion barrier to block the diffusion of the metal into the silicon. Owing to their high biostability, TiN layers may also be used as electrodes in bioelectronic applications.

Quick Facts

Product Titanium Nitride Sputtering Target

Stock No NS6130-10-1331 CAS 25583-20-4

Backing Plate (As per Customer requirement)

Additional Characteristics

Stock No.	Purity	Diameter	Thickness
NS6130-10-1331	99.99%	50.8 mm ± 1mm	3 mm ± 0.5mm

Technical Specification

Molecular Formula	Molecular Weight	Melting Point
TiN	61.87g/mol	2930°C











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ISO 9001:2015 CERTIFIED COMPANY

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